

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MIN-HSIU HUNG	04/19/2018
YI-HSIANG CHAO	04/19/2018
KUAN-YU YEH	04/19/2018
KAN-JU LIN	04/19/2018
CHUN-WEN NIEH	04/19/2018
HUANG-YI HUANG	04/19/2018
CHIH-WEI CHANG	04/19/2018
CHING-HWANQ SU	04/19/2018
RECEIVING PARTY DATA	
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City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16914638
CORRESPONDENCE DATA	
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NAME OF SUBMITTER:	DANIEL R. MCCLURE
SIGNATURE:	/Daniel R. McClure/

PATENT

DATE SIGNED:	06/29/2020
Total Attachments: 2 source=00803154#page1.tif source=00803154#page2.tif	

ASSIGNMENT

WHEREAS, Min-Hsiu HUNG, Yi-Hsiang CHAO, Kuan-Yu YEH, Kan-Ju LIN, Chun-Wen NIEH, Huang-Yi HUANG, Chih-Wei CHANG and Ching-Hwang SU

Here after referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR DEVICE WITH LOW RESISTIVITY CONTACT STRUCTURE AND METHOD FOR FORMING THE SAME

Filed: 2018-04-27 Serial No. 15/964,352

Executed on: _____

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., of No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C., hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2018.4.19 Min-Hsiu Hung
Date Name: Min-Hsiu HUNG

2018.4.19 Yi-Hsiang Chao
Date Name: Yi-Hsiang CHAO

2018-04-19 Kuan Yu Yeh
Date Name: Kuan-Yu YEH

2018 4/19 Kan Ju Lin
Date Name: Kan-Ju LIN

2018-04-19 Chun Wen Nieh
Date Name: Chun-Wen NIEH

2018-04-19 Huang Yi Huang
Date Name: Huang-Yi HUANG

2018-04-19 Chih-Wei Chang
Date Name: Chih-Wei CHANG

2018-04-19 Ching-Hwanq Su
Date Name: Ching-Hwanq SU